



cool new technology from



Suppress-n-Sink™

Dual Use RF Absorber + Thermal Pad

Suppress-n-Sink™ 300

MAST Technologies Suppress-n-Sink™ 300 materials are a new set of advanced dual purpose materials to be used for EMI/RF suppression and thermal conductance. The materials are formulated for high thermal conductivity as well as EMI/RF attenuation across a broad frequency range. The high thermal conductivity enables designers to mount this material directly on top of a silicon chip for heat transfer while also suppressing electromagnetic energy.

APPLICATIONS

- Suppress EMI from noisy chips
- Thermal Gap Pad
- Thermal Interface Material
- Sinking Hot Processor Chips to Heat Sinks
- Sinking Hot VGA Chips to Heat Sinks

FEATURES & BENEFITS

- Dual Use EMI and Thermal Pad
- Extremely soft for high low thermal resistance
- EMI absorption from 50 MHz to 4 GHz
- Broad Operating Temperature Range
- Wide range of thicknesses available

PART NUMBERING: MS32-XXXX-XX

Standard Part #	Thickness (inch/mm)	Frequency (GHz)
MS32-0001-00	0.020"/0.5	0.8 to 4
MS32-0002-00	0.040"/1.0	0.5 to 4
MS32-0003-00	0.060"/1.5	0.2 to 4
MS32-0004-00	0.080"/2.0	0.05 to 4

AVAILABILITY

- Standard Sheet Sizes: 8.25" x 11.5" (210 x 292mm)
Other sheets sizes under development
- Format: Sheets, Die Cut, Kiss Cut Pads

TYPICAL PROPERTIES

	Value	Test Method
Thickness (inches)	0.020" to 0.125"	
Thermal Conductivity (W/mK)	1.5	ASTM D5470
RF Absorption (power loss, %)	25% @ 1 GHz	
Hardness (Shore A)	24	ASTM D2240
Tensile Strength (Mpa)	>29	ASTM D412
Operating Temp. (°F)	-60 to 375	
Volume Resistivity (Ω—cm)	>10 ¹⁰	ASTM D991

All information on this data sheet is based on laboratory testing and is not intended for design purposes. MAST Technologies makes no representations or warranties of any kind concerning this data. For part number quality assurance specifications, please contact a MAST Technologies technical representative.

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